

SPIRE

SUBJECT: DRCU - Declared Components List (Flight Model)

PREPARED BY: V. Mauguen

DOCUMENT No: SPIRE-SAP-DOC-001075

ISSUE: 11 **Date:** 06th December 2001

CHECKED BY: C. Cara **Date:** 10/12/2001

Local Project Manager:

Project Manager:

Instrument Scientist:

Systems Engineer:

REFERENCE: SAp-SPIRE-VM-0051-01



**SPIRE/DRCU Instrument
Herschel Mission**



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

SPIRE Declared Components List

User Code: FSDRCC

06 December 2001

Edition: 11

Revision: 0

SAp-SPIRE-VM-0051-01

Prepared by :	Date :
V. Mauguen	
Checked by :	Date :
C. Cara	



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

Document change record

Révision			Modifications
Issue - rev.	Date	Approved by	
0	23/08/00		Preliminary List, including capacitors, connectors, crystals, diodes, integrated circuits, resistors, wires & cables, and miscellaneous. No quantities.
1	18/09/00		<ul style="list-style-type: none">Quantities for parts types: OP400, PM139, HS303, HS508BRH, HS1840, ADC7809, DAC 7545, HS-26C31, HS-26C32, FPGA, resistors and MAT02.components eliminated: HS-508ARH (new version: B), wires & cables, and miscellaneous.
2	9/10/00		Parts type to be eliminated: resistors CMS type SMC3 (obsolete)
3	27/10/00		<ul style="list-style-type: none">Obsolete parts for space: OP27, OP297, OP497, OP482, AD580, AD7545GStandardisation proposals: LM124 (instead of OP400) , AD565ATD (instead of 7545ARP, AD584TH (instead of AD580 & REF-02), SEI7809LPRP (instead of ADS7809).
4	29/11/00		Components definitely eliminated: OP27, OP297, OP497, OP482, HS1840 (obsolete) and AD584TE-LCC20 (to be replaced by AD584TH-TO99), and ADS7809 (replaced by 7809LPRP.
5	16/01/01		<ul style="list-style-type: none">new quantities (<u>more actual</u>), and for all parts we are sure to use, <u>including attritions</u>.Components definitely eliminated: OP400AY-DIP14 & LM124 (no accepted by CEA), AD580TH (no need)New components: UT54LVDS031 (item 18), UT54LVDS032 (item 19)Type reduction accepted: RT54SX32S-1 CQ208E (instead of all FPGA types).



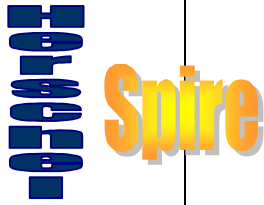
Spire

SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

6	02/01/01	<ul style="list-style-type: none">• Components definitely eliminated: HS1840; AD584TH (replaced by REF02AL) ; AD565 (standardisation refused) & 1N5617 (replaced by 1N4148)• New components: 1N4148 (item 1), 54HC137 (item 20), 54HC164 (item 21), HS117RH (item 22). For these new parts types, the package is to be confirmed.
7	14/03/01	<ul style="list-style-type: none">• a new colon “WIH” to identify cables/connectors for Warm Interbox Hardness (no crio harness). Today only connectors because cables not identified yet.• PM139: any need more (quantity: 0)• New connector type: HE801 144P• New colons for costing• Attrition for STM parts• Quantity identified for connectors accessories• Components eliminated of the list: ADS7809, OP400AY, AD584, AD589, old version of FPGAs.
8	14/06/01	<ul style="list-style-type: none">• New components: capacitor KM-94 220nF(item 19), 54HC595 (item 23), OP215 (item 24)• Quantities have changed for: UT54LVDS032, HS-508RH, MAT-02, HS-033RH, SEI7809, 26C31, 26C32, AMP02, 1N4148, 2N2222A, 2N2907A, 7545ARP• Components eliminated of the list:PM139• Components self-procured: OP400, DAC8800, REF02AL (only for QM) and OP15AL (only for QM) because don't exist in FP & QM quality level
9	23/07/01	<ul style="list-style-type: none">• new components: CMS1206 100nF (item 21) to replace CMS1210, CHPHR0505 10R (item 62), 1R (item 70), diode 1N6642, PHR0603 143K (item 72), 17K (item 73), 29K (item 74), 475R (item 75), 51.1K & 6.65K, CHPHR0805 1K (item 77), PHR0603 4K (item 78), fifo 16K*9 FP28 ref: 672061EV-15• Quantities have changed for: CHPP0603 200R (item 24), CHP0805 470pF, 47pF, CEC 47nF (item 10), KM94-1 220nF, OP400, TAJC 10µF 16V, HS508BRH, SEI7809LPRP, CMS1210 100nF, UT54LVDS031, OP215, TAJC 10µF 16v, REF02AL, CHPHR0805 100R & 10K, PHR0603 4.99K, CHPHR0805 200R



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

9	04/09/01	1	<ul style="list-style-type: none"> new components: OP15AL & AMP01 (parts types existing in PACS's list FPBOLC) quantities have changed for SEI 7545
10	23/10/01		<ul style="list-style-type: none"> new components: 54HC14 , MMDP-65656GV-40sB quantities have changed for AD590 parts eliminated: T1507 16MHz & 20MHz to replace by T807 20MHz correction of Part Number for SMDP-67206 modification for attrition rules (only for CHIP capacitors and resistors)
11	06/12/01		<ul style="list-style-type: none"> new components: <ul style="list-style-type: none"> Capacitor CMS 0805 T1 1,5nF (item 5) HE801 connectors: KNB0965510110 (item 10), KNB0964430121 (item 11), KNC1605510110 (item 14) & KNC1604430121 (item 15) - savers: KNB096 44 91 944 (item 24) & KNC160 44 91 944 (item 26) quartz 10 MHz T807 resistors: RLR07/2H4 1R (item 37) Chip CMS P0603 type P(0,01%) 9K76 (item 38), 13K3 (item 39), 17K4 (item 40), 18K2 (item 41), 27K4 (item 42), 61K (item 43), 90K9 (item 44), 95K3 (item 45), 97K6 (item 46) , 102K (item 47) & 267R (item 48). relays: type TL, GP2 & EL210 parts to be eliminated: <ul style="list-style-type: none"> quartz T1507 @ 11,0592 MHz (STC 3665) 3549_350100933B Chip CMS P0603 type P(0,01%): 200R (item 20), 475R (item 21), 6.65K (item 24), 8K (item 25), 16K9 (item 28), 28K7 (item 30), 65K (item 32), 143K (item 35) & 147K (item 36). CHPHR 0505: 10R2 (item 2), 10K (item 6). Capacitor CMS 0805 T1 470pF quantities have changed for: 2N2222, 2N5154, 1N5618, AD589, OP215, OP15, AD590 & HS508
			<ul style="list-style-type: none">



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

Distribution list

Ken King	RAL		2
Eva Diaz	TL		2
Olga Ramos	TL		2
Susanna Gadeano	TL		2
Giovanni Gallina	TP		2
			2
Christophe Cara	CEA / SAp		2
F. Pinsard	CEA / SAp		
			2
P. Levacher	LAM		2
			2



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

I. Acronyms

ABCL	As Built Configuration List	MOC	Mission Operations Centre
AD	Applicable Document	MOS	Margin Of Safety
AO	Announcement of Opportunity	MRB	Material Review Board
API	Application Programming Interface	N/A	Not Applicable
AIT	Assembly Integration & Test after delivery	NCR	Non Conformance Report
AIV	Assembly Integration & Verification before	OAT	Osservatorio Astronomico di Trieste
delivery		OBDH	On Board Data Handling
AVM	Avionics Model	OGS	Operational Ground Segment
BOL	Begin Of Life	PA	Product Assurance
CC	Configuration Control	PDF	Portable Document Format (Adobe Acrobat)
CCS	Central Checkout System	PFM	Proto-Flight Model
CIDL	Configuration Item Data List	PGSE	Pneumatic Ground Support Equipment
CEA	Commissariat à l'Énergie Atomique	PI	Principal Investigator
CMB	Cosmic Microwave background	PLM	Payload Module
Co-I	Co-Investigator	PM	Project Manager
COTS	Commercial Off The Shelf Software	PO	Parts Order
CQM	Cryogenic Qualification Model	PR	Public Relations
DMS	Document Management System	PS	Project Scientist
DPC	Data Processing Centres	PSF	Point-Spread-Function
DPCM	Data Processing Centres Manager	QA	Quality Assurance
EGSE	Electric Ground Support Equipment	QLA	Quick Look Analysis
EOL	End Of Life	RAL	Rutherford Appleton Laboratory
EP	Entrance Pupil	RD	Reference Document
ESA	European Space Agency	RFW	Request For Waiver
ESOC	European Space Operations Centre	RH	Relative Humidity
ESTEC	European Space Technology and Research Centre	RMS	Root Mean Square
FINDAS	FIRST Integrated Network And Data Archive System	RTA	Real Time Analysis
FIRST	Far InfraRed and Sub-millimetre Telescope	S/C	Spacecraft
FOV	Field-Of-View	SAMBA	Satellite for Measurement of Background Anisotropies
FPA	Focal Plane Assembly	SAp	Service d'Astrophysique
FPU	Focal Plane Unit	SCMP	Software Configuration Management Plan
FS	Flight Spares	SE	System Engineer
HK	House-Keeping	SIP	Science Implementation Plan
HTML	Hyper Text Mark-up Language	SPIRE	S
HTTP	Hyper Text Transport Protocol	SPMP	Software Project Management Plan
H/W	Hardware	SQAP	Software Quality Assurance Plan
ICD	Interface Control Document	SRR	Software Requirements Review
IDIS	Integrated Data and Information System	SS	Survey Scientist
IDIS-DT	IDIS Development Team	SSD	Space Science Department (ESTEC)
IDIS-MT	IDIS Management Team	S/W	Software
IID-A	Instrument Interface Document, Part A	TBC	To Be Confirmed
IID-B	Instrument Interface Document, Part B	TBD	To Be Determined
IS	Instrument Scientist	TBN	To Be Nominated
LAM	Laboratoire d'Astrophysique de Marseille	TBW	To Be Written
LAN	Local Area Network	TC	Tele-Command
LEOP	Launch & Early Orbit Phase	TM	TeleMetry
LM	Local Manager	TRB	Test Review Board
LOS	Line Of Sight	URD	User Requirements Document
MGSE	Mechanic Ground Support Equipment	WFE	Wave Front Error
		WWW	World Wide Web



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

II. Table of Contents

I. ACRONYMS.....	VI
II. TABLE OF CONTENTS	VII
1. INTRODUCTION	8
1.1 PURPOSE AND SCOPE	8
1.2 DOCUMENTS.....	8
1.2.1 <i>Applicable Documents</i>	8
1.2.2 <i>Reference Documents</i>	8
2. LEGEND OF LIST COLUMNS	9
3. RADIATION CONSTRAINTS	9
3.1 ABBREVIATIONS	9
4. LIST OF COMPONENT MANUFACTURERS.....	10
5. GENERAL ATTRITION RULES FOR FLIGHT AND SPARE MODELS	12
6. SPECIAL ATTRITION RULES FOR HIGH COST SEMICONDUCTOR PARTS	12
7. LIST OF PARTS.....	13
7.1 FAMILY CODES	13
.....	13



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

1. INTRODUCTION

1.1 Purpose and scope

This document provides a list of the electrical components which would be used in the flight model of the DRCU system (DCU & SCU).

The harness connectors are not included in this list, only savers on warm electronics and cryogenics connectors are included.

1.2 Documents

1.2.1 Applicable Documents

1.2.2 Reference Documents

- [RD1] ESA/SCC QUALIFIED PARTS LIST (15-01-00)
- [RD2] EUROPEAN PREFERRED PARTS LIST (15-02-00)
- [RD3] CNES / QFT / IN0500 Liste préférentielle des composants
- [RD4] FIRST/Planck Preferred Part List ref. : FP-TLG-LI-0001 (07-06-2000)



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

2. LEGEND OF LIST COLUMNES

Generic Name : Part Name

Manuf : Manufacturer

Pkg. : Preferred Package / Housing

Part Description : Details / Features of the component

Radiation Harness : Radiation marker

FLT Part Type: Flight Part Type

Preferred Proc-Spec : Preferred Procurement Specification

Level : Required Quality Level

LAT: Lot Acceptance Tests

FM parts : Quantity for Flight Model

FS parts : Quantity for Flight Spare

Needs CEA : Total quantity (PFM + FS)

Attr parts : Attrition quantity

PO : Total quantity for order (Needs CEA + Attr)

3. RADIATION CONSTRAINTS

3.1 Abbreviations

TD : Total Dose effects

SEE : Single Event Effect

SEU : Single Event Upset

SEL : Single Event Latch up (Soft error due to heavy ions)



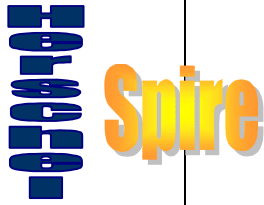
SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

4. LIST OF COMPONENT MANUFACTURERS

Code	Country	Manufacturer	Address / Seller
TBD		To Be Defined	
ACTEL	USA	Actel Corporation	
AD	USA	Analog Devices	1500 Space Park Drive CA 95052 Santa Clara USA Tel /Fax: 1(0)408 5627408/526 www.analog.com
ATMEL	USA	Atmel	
BB	USA	Burr Brown	
CAN	F	ITT Cannon	BP 359 Av; du Mal deLattre de Tassigny F-39105 DOLE Cedex Tel/Fax: 33(1)84729469/9593 www.ittcannon.com
CEPE	F	CEPE	C-MAC France 44, avenue de la Glacière BP165 F-95100 ARGENTEUIL Tel/Fax : 33(0)139983633/50 Cepe.com@hol.fr
EFD	F	Eurofarad	23, rue Jeanne d' Arc F-77400 LAGNY Te/Fax : 33(0)160317000/64305063 www.eurofarad.com
FCI	France	Framatome Connector International	3, rue de Vallon Hameau d'activités n°2 F-91550 Marolles-en-brie Tel/Fax: 33(0)145107844/40 www.fciconnect.com
FRB		Hypertac S.A.	31, rue Isidore Maille F-76410 St Aubin Les Elboeufs Tel/Fax: 33(0)232969176/70 www.frb-connectron.com Frb.connectron.ama@wanadoo.fr
HARRIS	USA	HARRIS	INTERSIL 2401 Palm Bay Road, N.E. FL 32905 Palm Bay USA Tel/Fax: 1(0)407 7279207/95361 www.semi.harris.com



SPIRE/DRCU Instrument Herschel Mission



Ref : Sap-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

HON	USA	Honeywell	12001 State Highway 55 MN 55441 PLYMOUTH USA Tel/Fax: 1(0)6129542888/257 www.honeywell.com
LCC	GB	LCC/AVX LTD	Long Road 7Q4 7ER Paignton Devon England Tel/fax : 44(0)1803528046/6223 www.avxcorp.com
LM	USA	Lockheed Martin	
LT	USA	Linear Technology	Mac Carthy Boulevard CA 95035 MILPITAS USA Tel/Fax: 1(0)4084321900/40507 www.linear-tech.com
MAXIM	USA	Maxim	
	USA	Microsemi	2830 S. Fairview Street PO Box 26890 CA 92704 Santa Anna Tel/Fax: 1(0)7149798220/5575989 www.microsemi.com
NS	USA	National Semiconductor	2900 Semiconductor Drive PO Box 58090 CA 95052 Santa Clara Tel/Fax: 1(0)4087215000/399803 www.national.com
SEI	USA	Space Electronic Inc.	REP' FRANCE
SFR	F	Sfernice	
TEMIC	F	Temec, Matra Harris	NANTES
TI	USA	Texas Instruments - Unitrode	7 Continental Boulevard NH 03054 MERRIMACK USA Tel/Fax: 1(0)034242410/3460 www.unitrode.com
VIS	F	Vishay S.A. division Sfernice	199, Bld de la Madeleine BP 1159 F-06003 NICE Cedex 1 Tel/fax: 33(0)493372727/26
VIT	F	Vitramon	



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
Date : 06/12/2001
Edition : 11
Revision : 0

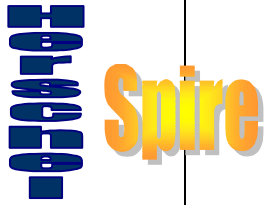
5. GENERAL ATTRITION RULES FOR FLIGHT AND SPARE MODELS

The following table shows the attrition quantities to be applied for parts families. For high cost semiconductor parts, the attrition quantities will be done case by case in the next chapter.

Net Quantity	Chip Capacitors and resistors	Other resistors, capacitors and filters	Semiconductors, relays and connectors with fixed contacts	Connectors bodies, saver bodies and crystals
1 - 5	+10	+4	+3	+2
6 - 8	+10	+5	+4	+2
9 - 15	+10	+6	+5	+3
16 - 25	+15	+7	+6	+4
26 - 40	+20	+10	+8	+5
41 - 60	+20	+13	+10	+6
61 - 100	+25	+17	+15	+10%
101 - 150	+25	+25	+20	+10%
151 - 250	+35	+37	+28	+10%
>= 251	+15%	+15%	+11%	+10%

6. SPECIAL ATTRITION RULES FOR HIGH COST SEMICONDUCTOR PARTS

High cost parts	Net Quantity : 1 - 5	Net Quantity : >5
PROM	+100%	+100%
FPGA RT54SX32S	+2	+4



SPIRE/DRCU Instrument Herschel Mission



Ref : SAp-SPIRE-VM-0051-01
 Date : 06/12/2001
 Edition : 11
 Revision : 0

7. LIST OF PARTS

7.1 Family Codes

Family Code	Group Code	Family	
01	01	Capacitors	Ceramic
	02	Capacitors	Ceramic Chip
	03	Capacitors	Tantalum Solid
02	01	Connectors	Circular
	02		Rectangular
	03		Printed Circuit Board
	07		Microminiature
03	01	Piezo-Electric Devices	Crystal Resonator
	99		Miscellaneous
04	01	Diodes	Switching
	02		Rectifier
	03		Voltage Regulator
	04		Voltage Reference
07	01	Inductors	RF Coils
	02		Cores
	03		Chip
08	10	Microcircuits	Microprocess/Microcontrol/
	20		Memory SRAM
	21		Memory DRAM
	22		Memory PROM
	23		Memory EPROM
	24		Memory EEPROM
	29		Memory Others
	30		Programmable Logic
	40		ASIC Technologies Digital
			ASIC Technologies Linear
			ASIC Technologies Mixed
		Linear Sample & Hold Amplifier	
	99		Miscellaneous

SPIRE Declared Components List Ed11

Flight Models

SPIRE / Herschel CEA Saclay, User Code: FSDRCC

<i>obsolete part for space, proposal (x)</i>																																		
* new components/last list																																		
<i>in italic: type proposal by Tecnologica, but not acceptable by CEA</i>																																		
Item N°	Family Code	Group Code	GENERIC NAME	comments	FLT Part Type	FLT Generic Spec	FLT Detail Spec	Level	evaluation	upscreening	Lat	Rad	FLT Description	Status	Manuf	Pkg	Attr.	Needs CEA	LLI	Total Need	PO	Self procure d	FM parts	FS parts										
												Tol											9 LIA_P	2 LIA-P										
																							3LIA-S	LIA-S										
																							2 BIAS	BIAS										
																							2 DAC	DAC-F										
																							1 BP	BP										
																							TEMP	TEMP										
																							2 CK-1/F	CK-1/F										
																							BP	BP										
																							distrib	distrib										
10	8-		HS-26C32RH		HS9-26C32RH-QS9000	MIL-PRF-38535	5962F9568901VXC	v				100K	Quad EIA RS422, Radiation Hardened CMOS, Differential Receiver, with 3-State Output	EPPL QML-38535	HAR/U	FP16	5	10	N	15			6	4										
18	8-		UT54LVDS031		UT54LVDS031	MIL-PRF-38535	5962R9583302VXC	v				1M	Quad CMOS Differential Line Driver, LVDS, Rad-Hard	QML-38535	NS	FP16	6	21	N	27			14	7										
19	8-		UT54LVDS032		UT54LVDS032	MIL-PRF-38535	5962R9583402VXC	v				300K	Quad CMOS Differential Line Receiver, LVDS	QML-38535	UTMC	FP16	15	66	N	81			52	14										
			FPGA																															
11c	8-		RT 54SX32S		RT54SX32S CQ208E	SA-0320-EYC	SMD + Mfr Amend					rt 75-100k	32000 Gates,SX-A Family, FPGA, RadTolerant and Hired	QML-38535	ACT/U	CQFP-208	4	12	N	16			10	2										
																						total without												
			Resistors																															
			RLR07/2H4 1% 100ppm 1/8W 200V																															
*	37		1R		2H4/RLR 07 1R	ESA/SCC 4001	ESA/SCC 4001/006-01	c					High Reliability, Resistor, Fixed, Film,non hermetically sealed based on type RLR07	EPPL	SFER		10	54		64			42	12										
			CHP HR 0505 1/8W 2% 50V +/-200 ppm																															
	4	10-	1R		CHPHR 0505 1R00 F6 BE	ESA/SCC 4001	ESA/SCC 4001/016-03	c					High reliability,Resistor, Fixed, Chip	EPPL	SFER	505	0	0	P	0			0	0										
			CHP HR 0505 1/8W 1% 50V +/-100 ppm																															
	2	10-	10R2		CHPHR 0505 10R2 F4 BE	ESA/SCC 4001	ESA/SCC 4001/016-03	c					High reliability,Resistor, Fixed, Chip	EPPL	SFER	505	25	112	P	137			90	22										
	3	10-	100R	0505 TBD	CHPHR 0505 100R0 F4	ESA/SCC 4001	ESA/SCC 4001/016-03	c					High reliability,Resistor, Fixed, Chip	EPPL	SFER	505	479.1	3194	P	3673			2562	632										
	4	10-	1K		CHPHR 0505 1K F4	ESA/SCC 4001	ESA/SCC 4001/016-03	c					High reliability,Resistor, Fixed, Chip	EPPL QPL ESA	SFER	505	71.7	478	N	550			384	94										
	5	10-	5K	4.99K	CHPHR 0505 5K F4	ESA/SCC 4001	ESA/SCC 4001/016-03	c					High reliability,Resistor, Fixed, Chip	EPPL QPL ESA	SFER	505	67.2	448	N	515			360	88										

SPIRE Declared Components List Ed11

Flight Models

SPIRE / Herschel CEA Saclay, User Code: FSDRCC

<i>obsolete part for space, proposal (x)</i>																								
* new components/last list																								
<i>in italic: type proposal by Tecnologica, but not acceptable by CEA</i>																								
Item N°	Family Code	Group Code	GENERIC NAME	comments	FLT Part Type	FLT Generic Spec	FLT Detail Spec	Level	evaluation	upscreening	Lat	Rad	FLT Description	Status	Manuf	Pkg	Attr.	Needs CEA	LLI	Total Need	PO	Self procure d	FM parts	FS parts
												Tol											9 LIA_P	2 LIA-P
																							3LIA-S	LIA-S
																							2 BIAS	BIAS
																							2 DAC	DAC-F
																							1 BP	BP
																							TEMP	TEMP
																							2 CK-1/F	CK-1/F
																							BP	BP
																							distrib	distrib
	9-	17	TL		TL 2PDT 1A 12V 500R 2ms	ESA/SCC 3602	ESA/SCC 3602/002						Relays, Electromagnetic, latching 28Vdc, 1A, 2PDT, TO5 CAN	QPL ESA EPPL	Deutsch	TO5		40		40			20	20
	9-	17	GP2		GP2 2PDT 2A 12V 180R 4ms	ESA/SCC 3602	ESA/SCC 3602/003-02	B					Relays, Electromagnetic, latching 28Vdc, 2A, 2PDT, half size crystal can	QPL ESA EPPL	Leach Inter	alf-crystal		14		14			7	7
	9-	17	EL210		EL210 2PDT 10A 12V 60R 15ms	ESA/SCC 3602	ESA/SCC 3602/009-06	B					Relays, Electromagnetic, latching 28Vdc, 15A, 2PDT	QPL ESA EPPL	Deutsch	gaure-inch		12		12			6	6
	9-	16	EL210			ESA/SCC 3601	ESA/SCC 3601/017						Relays, Electromagnetic, non latching 28Vdc, 15A, 2PDT	QPL ESA EPPL	Deutsch			12		12			6	6